
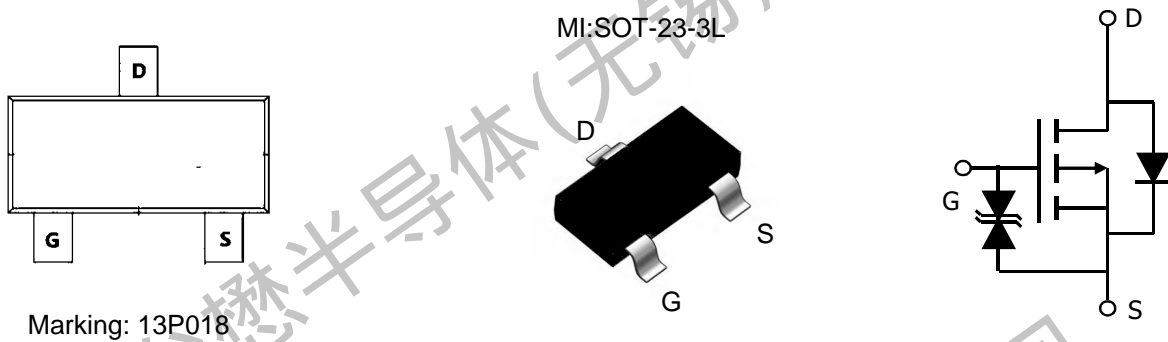


**TM13P018MI**

**P-Channel Enhancement Mosfet**

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = -18V</math> <math>I_D = -13A</math></p> <p><math>R_{DS(ON)} = 10m\Omega</math> (typ.) @ <math>V_{GS} = -4.5V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p> 
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**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-18	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V$	-13	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V$	-8.3	A
$I_{DM}$	Pulsed Drain Current	-33	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	1.6	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	80	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	---	$^\circ C/W$

**TM13P018MI**
**P-Channel Enhancement Mosfet**
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

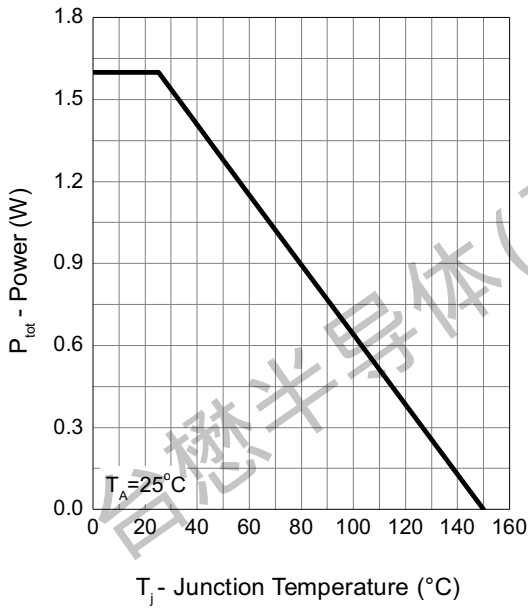
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=-250\mu A$	-18	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-9.6V, V_{GS}=0V$	-	-	-1	$\mu A$
		$T_J=85^\circ\text{C}$	-	-	-30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-0.5	-	-1.0	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=-4.5V, I_{DS}=-9.1A$	-	10	13	m $\Omega$
		$V_{GS}=-2.5V, I_{DS}=-6A$	-	15	18	
<b>Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_{SD}=-1A, V_{GS}=0V$	-0.4	-0.65	-1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=-6.3A,$	-	31	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI_{SD}/dt=100A/\mu s$	-	12	-	nC
<b>Dynamic Characteristics</b>						
$R_g$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	3	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=-6V,$ Frequency=1.0MHz	-	1514	-	pF
$C_{oss}$	Output Capacitance		-	373	-	
$C_{rss}$	Reverse Transfer Capacitance		-	286	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=-6V, R_L=6\Omega,$ $I_{DS}=-1A, V_{GEN}=-4.5V,$ $R_G=6\Omega$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	13	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	54	-	
$t_f$	Turn-off Fall Time		-	50	-	
<b>Gate Charge Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS}=-6V, V_{GS}=-4.5V,$ $I_{DS}=-6.3A$	-	14.5	-	nC
$Q_{gs}$	Gate-Source Charge		-	1.8	-	
$Q_{gd}$	Gate-Drain Charge		-	4	-	

TM13P018MI

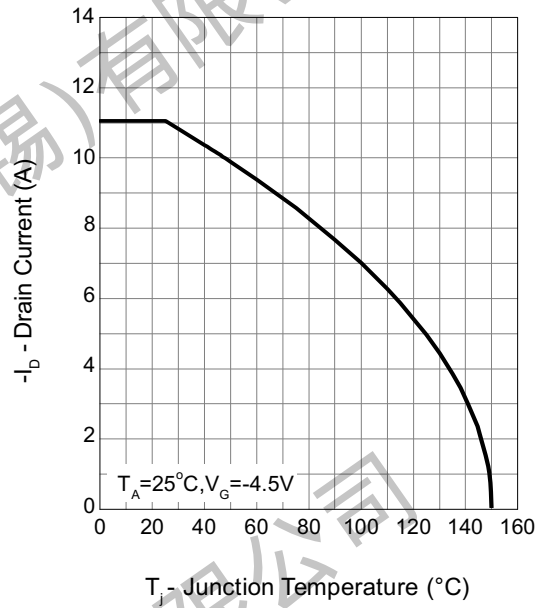
P-Channel Enhancement Mosfet

Typical Operating Characteristics

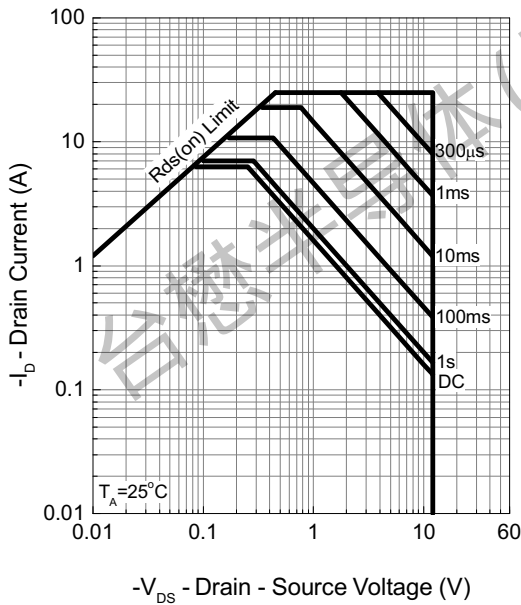
Power Dissipation



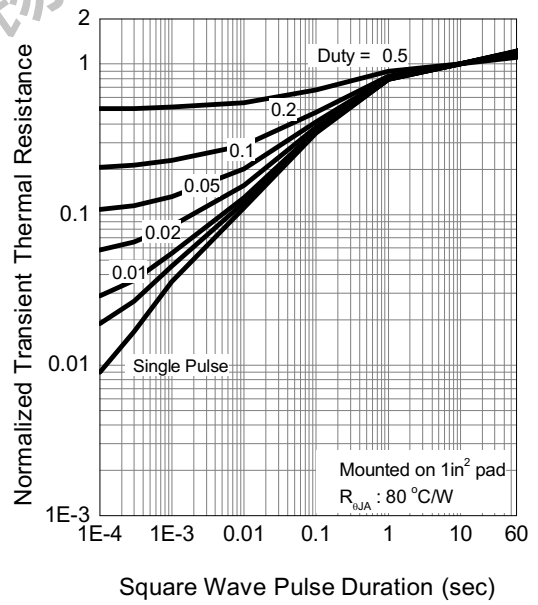
Drain Current



Safe Operation Area

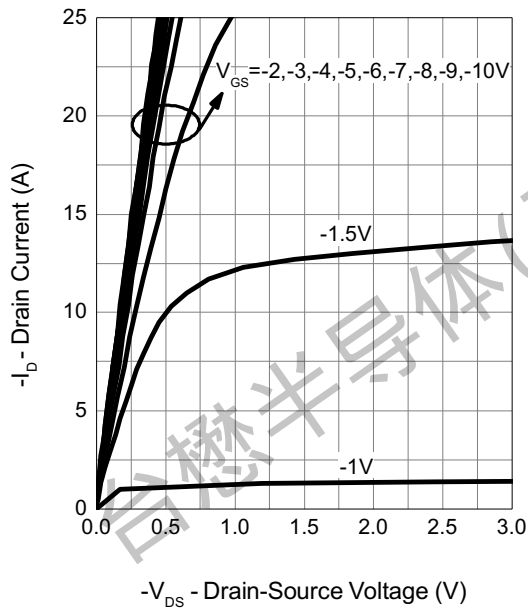


Thermal Transient Impedance

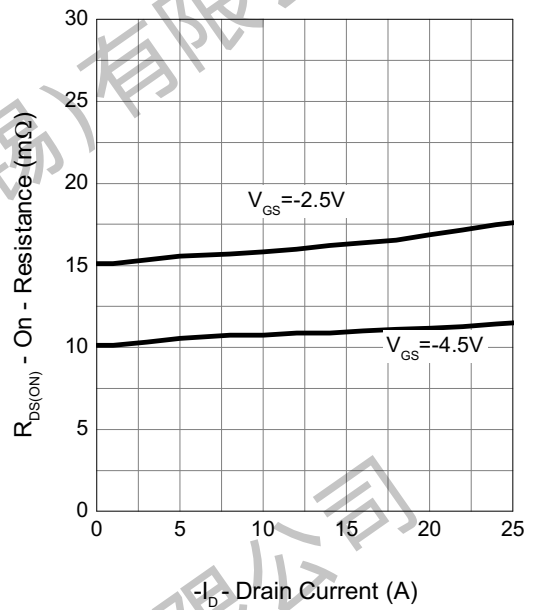


### Typical Operating Characteristics (Cont.)

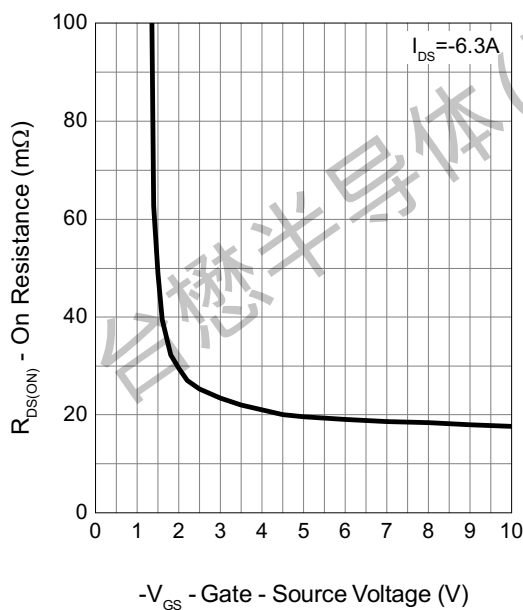
Output Characteristics



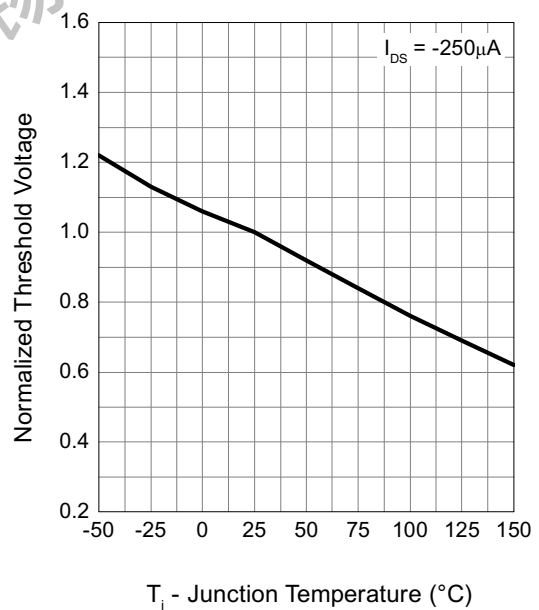
Drain-Source On Resistance



Gate-Source On Resistance

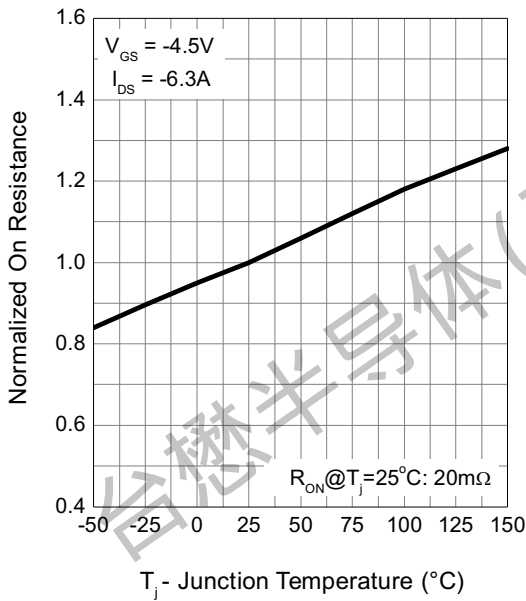


Gate Threshold Voltage

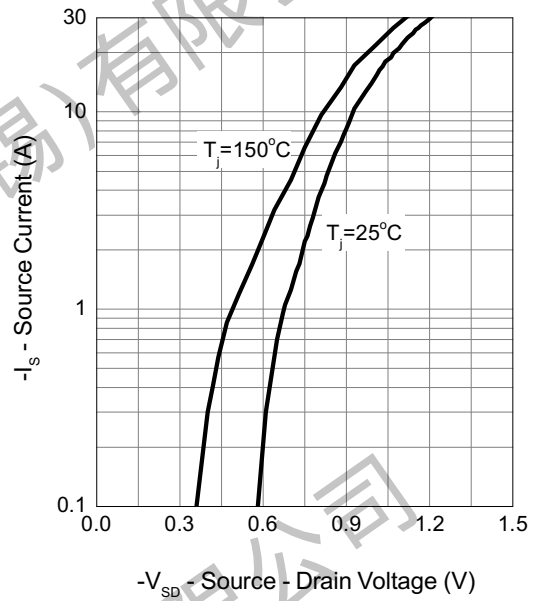


Typical Operating Characteristics (Cont.)

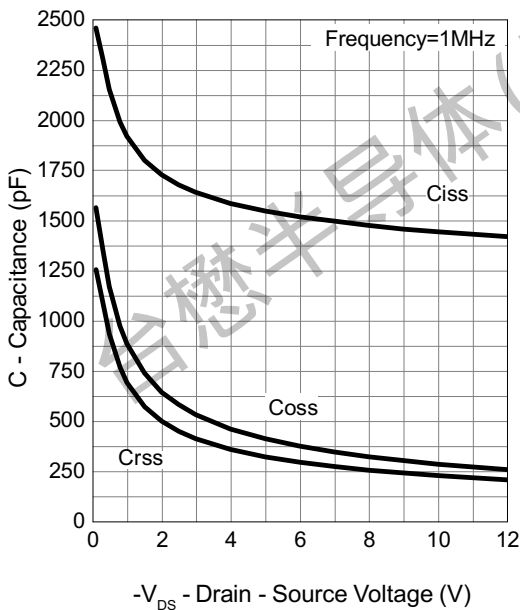
Drain-Source On Resistance



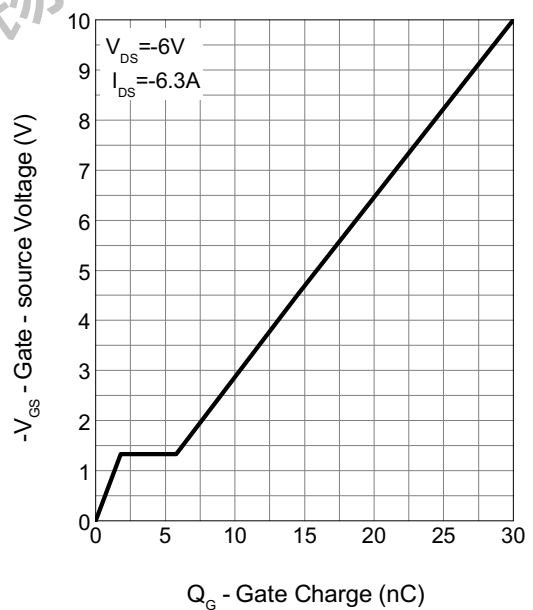
Source-Drain Diode Forward



Capacitance



Gate Charge

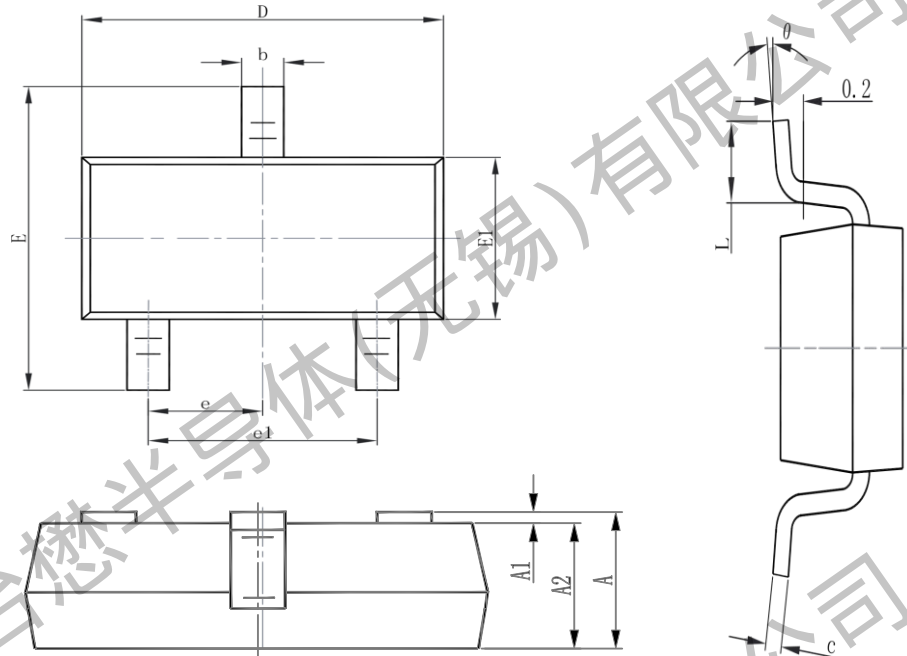




TM13P018MI

P-Channel Enhancement Mosfet

Package Mechanical Data:SOT-23-3L



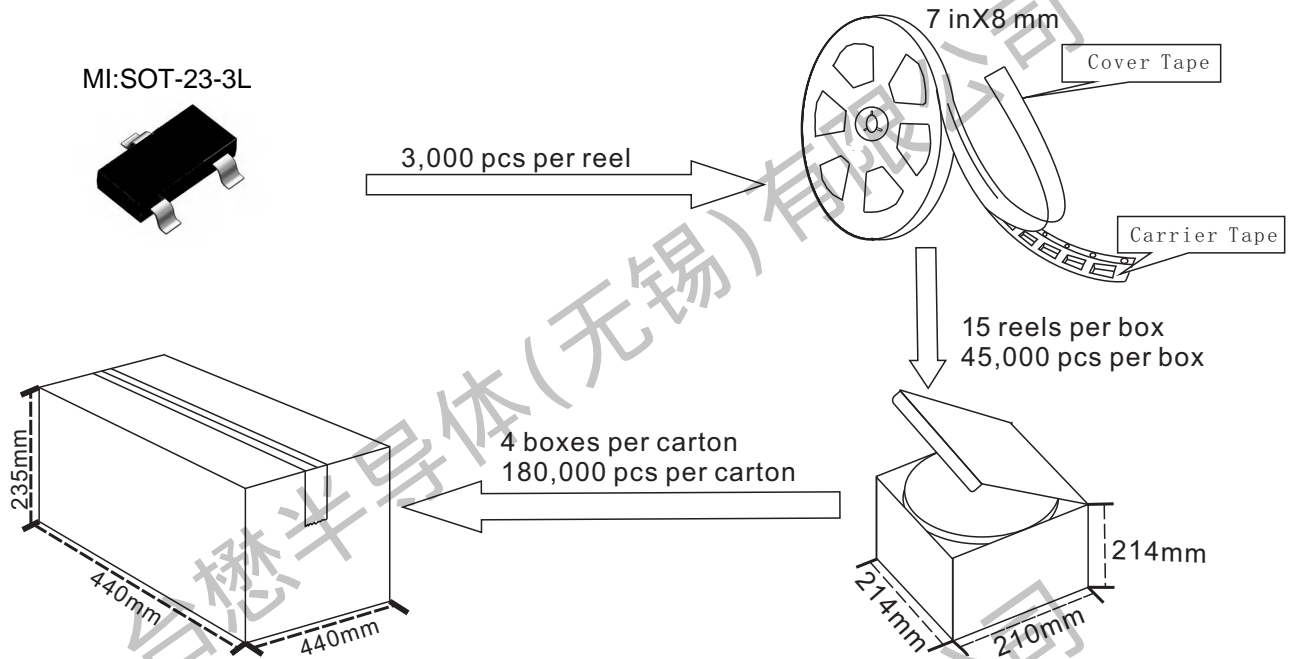
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

**TM13P018MI**

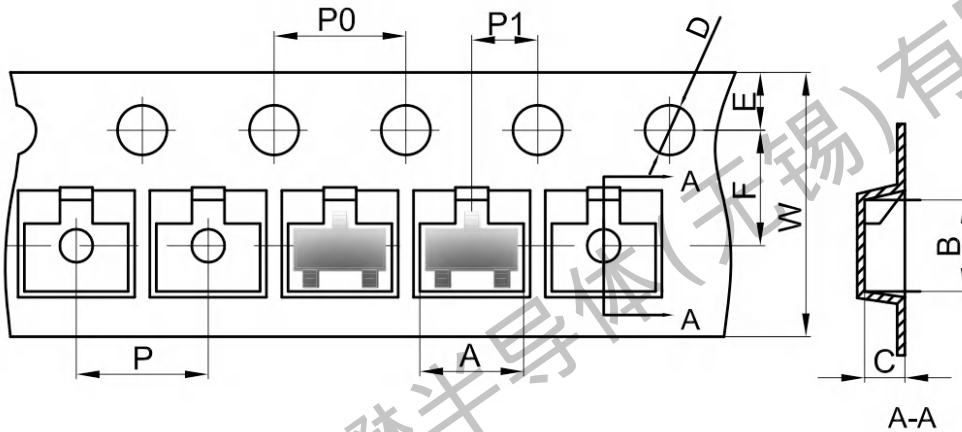
**P-Channel Enhancement Mosfet**

**SOT-23-3L Packing**

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)



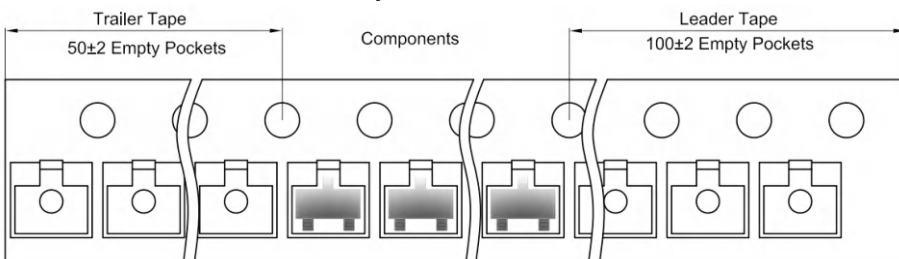
**SOT-23-3L Embossed Carrier Tape**



Dimensions are in millimeter

Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23-3L	3.15	2.77	1.22	∅1.50	1.75	3.50	4.00	4.00	2.00	8.00

**SOT-23-3L Tape Leader and Trailer**





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Revision history:

Date	Rev	Description	Page
2023.06.29	23.06	Original	